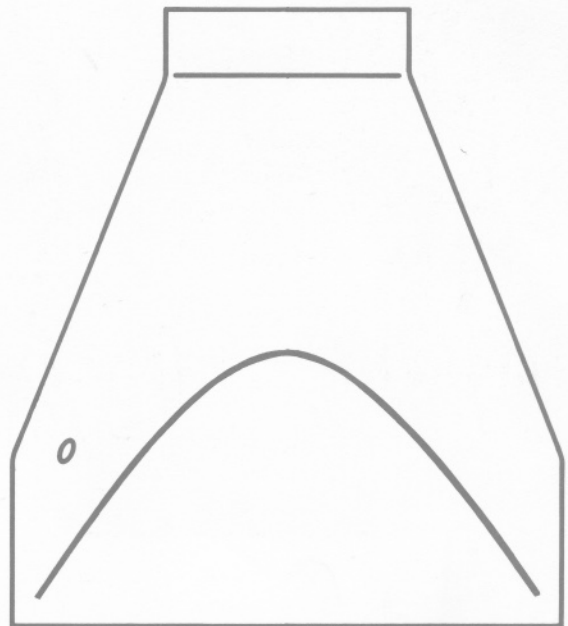
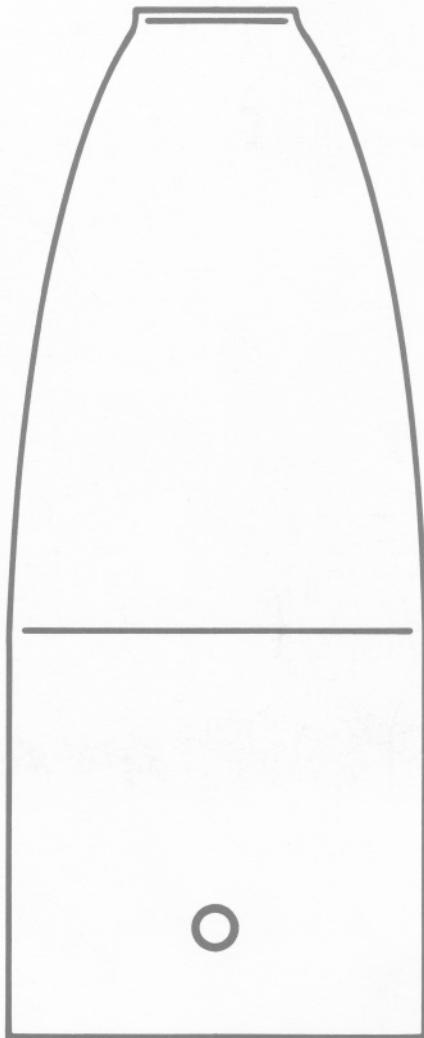


# THE CERAMIC ALTERNATIVE



**Tektronix**<sup>®</sup>  
COMMITTED TO EXCELLENCE

## Multilayer Ceramic Packaging Material Characteristics

Item	Units	96% Al <sub>2</sub> O <sub>3</sub> (High Fire)	Glass/Ceramic (Low Fire)
Color		White	White
Alumina Content	%	96	25
Specific Gravity	g/cm <sup>3</sup>	3.73	2.56

### Electrical

Dielectric Constant (1 MHz)		9.6	<del>5.4</del> 5.8
Dissipation Factor (1 MHz)	(x 10 <sup>-4</sup> )	15	16
Dielectric Strength	Volts/mils	550	808
Volume Resistivity (20°C)	Ohm-cm	> 10 <sup>14</sup>	> 10 <sup>14</sup>
(300°C)	Ohm-cm	1.4x10 <sup>11</sup>	1.8x10 <sup>10</sup>
(500°C)	Ohm-cm	7.9x10 <sup>8</sup>	1.3x10 <sup>8</sup>

### Thermal

Coefficient of Thermal Expansion (25-500°C)	(x10 <sup>-6</sup> /°C)	7.2	4.6
Thermal Conductivity (20°C)	Watt/meter·°K	23	2

### Mechanical

Hardness	R45N	81	
Flexural Strength	PSI	60,000	20,000
Compressive Strength	PSI	320,000	
Tensile Strength	PSI	27,000	

## Heat Sink Materials Thermal Properties

Material	Composition by Weight (%)			Thermal Coefficient of Expansion 25-400°C (ppm)	Thermal Conductivity (Cal/cm sec·°C)
	Tungsten	Copper	Nickel		
Tungsten Copper Nickel	90	8	2	6.89	0.45
Tungsten Copper Nickel	80	18	2	8.52	0.52
Alumina 96%	N/A	N/A	N/A	7	0.05
*BeO (99.5%)	N/A	N/A	N/A	7.5	0.6
*Aluminum	N/A	N/A	N/A	23	0.53

\* Tektronix does not manufacture BeO or Aluminum (included for reference purposes only).

# Alumina Ceramics

## Physical and Electrical Properties

Properties		Units	Alumina		
Alumina Content		%	90	90	96
Specific Gravity		g/cm <sup>3</sup>	3.75	3.51	3.71
Hardness	Rockwell	R45N	78	76	81
Surface Finish	As Fired	Microinches	26	24	24
Crystal Size	Average	Micrometers	3	3	4
Water Absorption			None	None	None
Gas Permeability			None	None	None
Color			Black	White	White
Compressive Strength	25°C	KPSI	340	380	405
Flexural Strength	25°C	KPSI	37	37	41
Tensile Strength	25°C	KPSI	22	24	25
Modulus of Elasticity		10 <sup>6</sup> PSI	45	39	48
Shear Modulus			17	16	20
Poisson's Ratio		10 <sup>6</sup> PSI	0.30	0.24	0.21
Max. Use Temperature	No Load	°C	1450	1525	1610
Coefficient of Linear Thermal Expansion		25–500°C	10 <sup>-6</sup> /°C		
			7.4	7.1	7.2
Thermal Conductivity		20°C	Cal/cm·sec·°C	0.04	0.04
Specific Heat			Cal/g·°C	0.23	0.21
Dielectric Strength		0.025 in. Thick	AC (Volts/mil)	460	620
Dielectric Constant		1 kHz		24.2	8.7
		1 MHz		9.7	8.6
		1 GHz		9.5	8.5
Dissipation Factor		1 kHz		0.2932	0.0036
		1 MHz		0.0470	0.0019
		1 GHz		0.0030	0.0019
Loss Index		1 kHz		7.095	0.031
		1 MHz		0.457	0.016
		1 GHz		0.028	0.016

## Sputtering Target Materials

	Density	Composition	Purity	Sizes
<b>Indium-Tin Oxide</b>	>90% of Theoretical	On Demand	99.8% (Higher Purity Available)	On Demand
Conductivity of Target: >10 <sup>4</sup> (Ω cm) <sup>-1</sup>				
<b>Titanium-Tungsten</b>	>90% of Theoretical	On Demand	Mobil Ions (Sodium, Potassium) >1 PPM. Lower mobil ion concentration available. Oxygen Concentration <0.2% (Higher Purity Available)	On Demand
CV Shift: <200 mV. Lower shift available with higher purity starting materials.				
<b>Superconducting</b>	70 to >90% of Theoretical	YBa <sub>2</sub> Cu <sub>3</sub> O <sub>7-x</sub> (1-2-3)	99.90% (Higher Purity Available)	1 to 8"
<b>Nichrome</b>	60 to >90% of Theoretical	On Demand Al Doping	99.90% (Higher Purity Available)	On Demand

# Forsterite Ceramics

## Physical and Electrical Properties

Properties		Units	Forsterite				
			B3-91	B3-94	B3-98	XR-1	
Tektronix Number							
Specific Gravity		g/cm <sup>3</sup>	2.82	2.82	2.82	3.06	
Hardness	Rockwell	R45N	65	60	56	60	
Surface Finish	As Fired	Microroches	41	48	42	66	
Crystal Size	Average	Micrometers	1	1	1	1	
Water Absorption			None	None	None	None	
Gas Permeability			None	None	None	None	
Color			Light Pink	Buff	Light Blue	Russet	
Compressive Strength	25°C	KPSI	195	170	195	165	
Flexural Strength	25°C	KPSI	21	21	20	19	
Tensile Strength	25°C	KPSI	13	13	12	12	
Modulus of Elasticity		10 <sup>6</sup> PSI	18	18	19	17	
Shear Modulus			8	7	7	7	
Poisson's Ratio		10 <sup>6</sup> PSI	0.21	0.25	0.26	0.25	
Max. Use Temperature	No Load	°C	1225	1225	1225	1225	
Coefficient of Linear Thermal Expansion		25-500°C	10 <sup>-6</sup> /°C	9.3	9.6	10.0	9.6
Thermal Conductivity	20°C	Cal/cm·sec·°C	0.008	0.008	0.008	0.008	
Specific Heat		Cal/g·°C	—	—	—	—	
Dielectric Strength	0.025 in. Thick	AC (Volts/mil)	560	720	560	—	
Dielectric Constant	1 kHz		6.3	6.3	6.3	—	
	1 MHz		6.2	6.3	6.2	6.8	
	1 GHz		6.2	6.1	6.2	—	
Dissipation Factor	1 kHz		0.0057	0.0049	0.0047	—	
	1 MHz		0.0025	0.0020	0.0017	0.0006	
	1 GHz		0.0031	0.0029	0.0023	—	
Loss Index	1 kHz		0.036	0.031	0.030	—	
	1 MHz		0.016	0.013	0.011	0.004	
	1 GHz		0.019	0.018	0.014	—	
Volume Resistivity	25°C		4.0×10 <sup>15</sup>	6.0×10 <sup>15</sup>	8.0×10 <sup>15</sup>	2.6×10	
	300°C	Ohms-cm <sup>2</sup> /cm	1.0×10 <sup>8</sup>	1.0×10 <sup>8</sup>	9.0×10 <sup>7</sup>	3.0×10	
	500°C		3.0×10 <sup>6</sup>	3.0×10 <sup>6</sup>	3.0×10 <sup>6</sup>	5.0×10	

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